

IN THE CLAIMS

Please cancel Claims 2 and 15 without prejudice or disclaimer.

Please amend the claims as follows:

Claim 1 (Amended). A semiconductor assembly, comprising:

a leadframe;

a die coupled to the leadframe;

[at least one] a plurality of channels formed in a top surface of the leadframe for promoting adhesion; [and]

a mold compound for encapsulating the semiconductor assembly wherein the mold compound flows into the [at least one] plurality of channels and bonds with the [at least one] plurality of channels forming a lock between the mold compound and the leadframe to prevent delamination of the semiconductor assembly;

a first raised area on the leadframe where the die is coupled; and

a plurality of second raised areas on the leadframe used for wirebonds wherein the plurality of second raised areas allow the mold compound to get underneath the wirebonds and capture the wirebonds to increase reliability of the wirebonds.

New cho thi co thi cho tuu claim 1
b/c Miramio & co's. 2nd raised area for wirebonds
on the rest of ind. claims lead on Miramio.

8-9, 11 Yamada

10 Yamada + H

12, 13 Y + Nakemichi

14 Yamada + H

14 Y +

24 + 25 = 8-9 Yamada

Claim (8) (Amended). A mounting for a semiconductor package, comprising:

a leadframe; and

at least one channel formed in a top surface of the leadframe wherein the at least one channel prevents delamination of the semiconductor package by allowing a mold compound to flow into the at least one channel and bonds with the at least one channel forming a lock between the mold compound and the leadframe.

Claim (14) (Amended). A mounting for a semiconductor package, comprising:

a leadframe; [and]

means formed on the leadframe for forming a lock between the leadframe and a mold compound which flows into the means;

a raised area on the leadframe forming a die pad; and
means for allowing a mold compound to get underneath wirebonds on the leadframe and capture the wirebonds.

CLEAN VERSION OF AMENDED CLAIMS

Claim 1. A semiconductor assembly, comprising:

a leadframe;

a die coupled to the leadframe;

a plurality of channels formed in a top surface of the leadframe for promoting adhesion;

B¹ a mold compound for encapsulating the semiconductor assembly wherein the mold compound flows into the plurality of channels and bonds with the plurality of channels forming a lock between the mold compound and the leadframe to prevent delamination of the semiconductor assembly;

a first raised area on the leadframe where the die is coupled; and

a plurality of second raised areas on the leadframe used for wirebonds wherein the plurality of second raised areas allow the mold compound to get underneath the wirebonds and capture the wirebonds to increase reliability of the wirebonds.

Claim 8. A mounting for a semiconductor package,
comprising:

a leadframe; and

BZ at least one channel formed in a top surface of the
leadframe wherein the at least one channel prevents delamination of
the semiconductor package by allowing a mold compound to flow into
the at least one channel and bonds with the at least one channel
forming a lock between the mold compound and the leadframe.

Claim 14. A mounting for a semiconductor package,
comprising:

B3 a leadframe;

means formed on the leadframe for forming a lock between
the leadframe and a mold compound which flows into the means;

a raised area on the leadframe forming a die pad; and

means for allowing a mold compound to get underneath
wirebonds on the leadframe and capture the wirebonds.
